

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ATAPOL PRAJUCKAMOL	09/26/2018
CHEE HIONG CHEW	09/26/2018
YUSHUANG YAO	09/26/2018
RECEIVING PARTY DATA	
Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
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Internal Address:	MAILDROP A700
City:	PHOENIX
State/Country:	ARIZONA
Postal Code:	85008
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17247200
CORRESPONDENCE DATA	
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Correspondent Name:	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
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Address Line 2:	MAILDROP A700
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ATTORNEY DOCKET NUMBER:	ONS02981C01US
NAME OF SUBMITTER:	SHARRON CASTILLO
SIGNATURE:	/Sharron Castillo/
DATE SIGNED:	12/03/2020
Total Attachments: 5	
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PATENT

REEL: 054535 FRAME: 0433

ASSIGNMENT & AGREEMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we,

Name _____ of (City and State OR Country) _____

ATAPOL PRAJUCKAMOL	KLAENG THAILAND
CHEE HIONG CHEW	SEREMBAN MALAYSIA
YUSHUANG YAO	SHENZHEN CHINA

agree to sell, assign, and transfer, and do hereby sell, assign, and transfer to Semiconductor Components Industries, LLC, a limited liability company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives ("SCI"), the entire right, title, and interest in and to the inventions and discoveries as described, illustrated, and/or claimed in

Title: **CONNECTING CLIP DESIGN FOR PRESSURE SINTERING**

Attorney Docket No.: **ONS02981U5**

Serial No.: 16/145517

Filing Date: September 28, 2018


together with the entire right, title, and interest in and to the above listed application(s), and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, international, foreign, and any and all other applications related thereto, and also including any and all grants, issuances, letters patent, reissues, reexaminations, renewals, priority rights, and priority claims related to any of the foregoing, and any and all rights to collect past damages for infringement of any of the foregoing (the "Patent Rights").

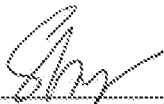
We further authorize SCI to apply for and hold and maintain the Patent Rights throughout the world directly in its own name or any other name which SCI deems appropriate in its sole discretion, and to claim the priority of the filing date of the above listed application(s).

We agree that, when requested, we will, without charge to SCI, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing, maintaining, and enforcing the Patent Rights in any and all countries and for vesting title thereto in SCI or its nominees.

We represent and warrant that we have full right to convey the entire right, title and interest herein sold, assigned, and transferred, and that the Patent Rights hereby conveyed are free from all prior assignment, grant, mortgage, license, or other encumbrance to anyone other than SCI. We covenant and further warrant that we will not convey hereafter any part of the Patent Rights to anyone other than SCI or do any act whatsoever conflicting with this ASSIGNMENT & AGREEMENT.

We hereby authorize SCI or anyone it may properly designate to insert in this ASSIGNMENT & AGREEMENT the filing date and serial number of the above listed application(s) when ascertained. More than one counterpart of this ASSIGNMENT & AGREEMENT may be executed, each of which will be deemed an original.

By (Inventor signature):  _____
Atapol Prajuckamol

Witnessed by (Witness signature):  _____

Printed name of Witness: Somporn Nopsiron

Signed and Witnessed on (date): 26 / 9 / 2012

By (Inventor signature): _____
Chee Hiong Chew

Witnessed by (Witness signature): _____

Printed name of Witness: _____

Signed and Witnessed on (date): _____

By (Inventor signature): _____
Yushuang Yao

Witnessed by (Witness signature): _____

Printed name of Witness: _____

Signed and Witnessed on (date): _____

By (Inventor signature): _____

Atapol Prajuckamol

Witnessed by (Witness signature): _____

Printed name of Witness: _____

Signed and Witnessed on (date): _____

By (Inventor signature): _____

Chee Hiong Chew

Witnessed by (Witness signature): _____

Printed name of Witness: WANG, SOON WEI

Signed and Witnessed on (date): _____

By (Inventor signature): _____

Yushuang Yao

Witnessed by (Witness signature): _____

Printed name of Witness: _____

Signed and Witnessed on (date): _____

ASSIGNMENT & AGREEMENT

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Name _____ of (City and State OR Country) _____

ATAPOL PRAJUCKAMOL	KLAENG THAILAND
CHEE HIONG CHEW	SEREMBAN MALAYSIA
YUSHUANG YAO	SHENZHEN CHINA

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Title: **CONNECTING CLIP DESIGN FOR PRESSURE SINTERING**

Attorney Docket No.: **ONS02981US**

Serial No.: **16/145517**

Filing Date: **September 28, 2018**

together with the entire right, title, and interest in and to the above listed application(s), and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, international, foreign, and any and all other applications related thereto, and also including any and all grants, issuances, letters patent, reissues, reexaminations, renewals, priority rights, and priority claims related to any of the foregoing, and any and all rights to collect past damages for infringement of any of the foregoing (the "Patent Rights").

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By (Inventor signature): _____

Atapol Prajuckamol

Witnessed by (Witness signature): _____

Printed name of Witness: _____

Signed and Witnessed on (date): _____

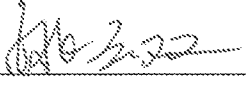
By (Inventor signature): _____

Chee Hiong Chew

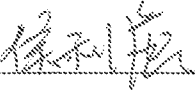
Witnessed by (Witness signature): _____

Printed name of Witness: _____

Signed and Witnessed on (date): _____

By (Inventor signature):  _____

Yushuang Yao

Witnessed by (Witness signature):  _____

Printed name of Witness: Eric Mou

Signed and Witnessed on (date): 26/9/2018